



GAU: 1104
#7/IDS 2100
PATENT 4/29
Docket No. 420099-654
LSI Logic No. P-2880/1D

I hereby certify that this correspondence and the attachment are being deposited with the United States Postal Service as First Class Mail on February 12, 1998, in an envelope addressed to: Honorable Commissioner of Patents and Trademarks, Washington, D.C., 20231.

Cheryle A. Healion
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FEB 24 1998

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application Of:

MIKE LIANG

Serial Number: 08/909,312

Filing Date: August 14, 1997

Entitled: **METHOD FOR DISTRIBUTING
CONNECTION PADS ON A
SEMICONDUCTOR DIE
(AS AMENDED)**

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GROUP 2200

Group Art Unit: 1104

Examiner:

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

SECOND SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

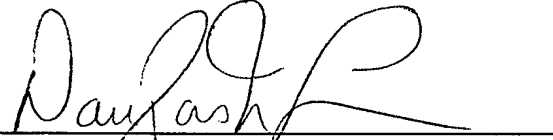
Sir:

Submitted herewith are one sheet of Form PTO-1449 and one copy of each of the patent documents listed therein for the above-captioned divisional application.

It is respectfully requested that the Examiner make his consideration of these documents formally of record with his initial action.

If any fees are due with this Second Supplemental Information Disclosure Statement, the Commissioner is authorized to charge them to Deposit Account Number 16-2230.

Respectfully submitted,



Douglas N. Larson
Registration No. 29,401

Dated: February 12, 1998

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